

## N-Channel Trench Power MOSFET

### Features

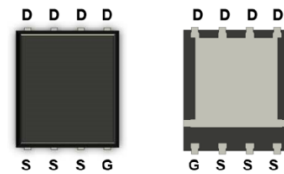
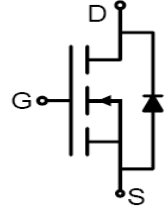
- 60V, 80A,  $R_{DS(ON)}=8m\Omega@V_{GS}=10V$
- Reliable and Rugged
- Advanced trench process technology High Density Cell Design For Ultra Low On-Resistance

### Application

- Battery protection
- Power management

### Product Summary

$V_{DS}$	60V
$R_{DS(on)}@V_{GS}=10V$	8m $\Omega$
$I_D$	80A



DFN5X6-8L

Package Not to Scale

### Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	60	V
Continuous drain current $T_C = 25^\circ\text{C}$ (Silicon limit) $T_C = 25^\circ\text{C}$ (Package limit) $T_C = 100^\circ\text{C}$ (Silicon limit)	$I_D$	- 80 47.5	A
Pulsed drain current $T_C = 25^\circ\text{C}$ , $t_p$ limited by $T_{jmax}$	$I_{D\ pulse}$	175	
Avalanche energy, single pulse ( $L=0.5mH, R_g=25\Omega$ )	$E_{AS}$	150	mJ
Gate-emitter voltage	$V_{GS}$	$\pm 20$	V
Power dissipation $T_C = 25^\circ\text{C}$	$P_{tot}$	115	W
Operating junction and storage temperature	$T_j, T_{stg}$	-55~175	$^\circ\text{C}$

### Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal resistance, junction – case. Max	$R_{thJC}$	2.5	°C/W
Thermal resistance, junction – ambient. Max	$R_{thJA}$	50	

### Electrical Characteristic, at $T_j = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Test Condition	Value			Unit
			min.	typ.	max.	

#### Static Characteristic

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	60	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$ $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$	2	3	4	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$ $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$	-	-	1 50	$\mu A$
Gate-source leakage current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-100	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=40A,$ $T_j=25^\circ\text{C}$	-	7	8	$m\Omega$
Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=40A$	-	100	-	S

#### Dynamic Characteristic

Input Capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=25V,$ $f=1\text{MHz}$	-	3200	-	pF
Output Capacitance	$C_{oss}$		-	360	-	
Reverse Transfer Capacitance	$C_{rss}$		-	275	-	
Gate Total Charge	$Q_G$	$V_{GS}=10V, V_{DS}=25V,$ $I_D=30A, f=1\text{MHz}$	-	82	-	nC
Gate-Source charge	$Q_{gs}$		-	12	-	
Gate-Drain charge	$Q_{gd}$		-	32	-	
Turn-on delay time	$t_{d(on)}$	$T_j=25^\circ\text{C}, V_{DD}=25V,$ $I_{DS}=30A, R_L=3\Omega$	-	16	-	ns
Rise time	$t_r$		-	14	-	
Turn-off delay time	$t_{d(off)}$		-	21	-	
Fall time	$t_f$		-	32	-	
Gate resistance	$R_G$	$V_{GS}=0V, V_{DS}=0V,$ $f=1\text{MHz}$	-	1.8	-	$\Omega$

#### Body Diode Characteristic

Maximum Continuous Drain to Source Diode Forward Current	$I_S$		-	-	80	A
Maximum Pulsed Drain to Source Diode Forward Current	$I_{SM}$		-	-	175	A
Drain to Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=40A$	-	0.8	1.0	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F=20A,$ $dI/dt=100A/\mu s$	-	35	-	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	60	-	nC

## Typical Performance Characteristics

Figure 1: Power Dissipation

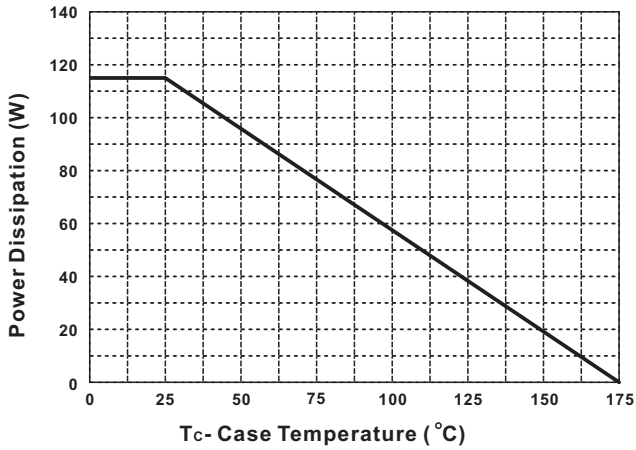


Figure 2: Drain Current

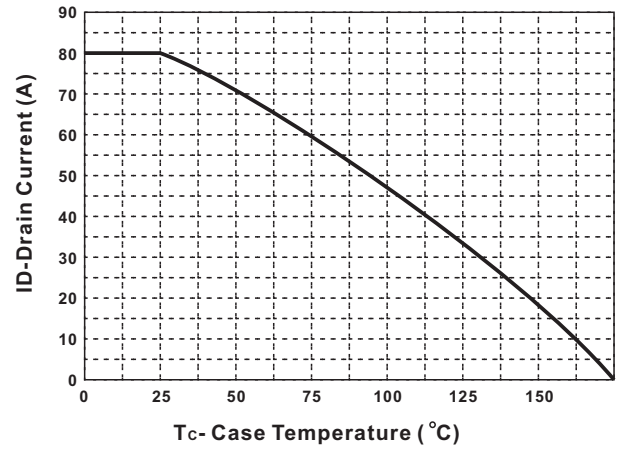


Figure 3: Safe Operation Area

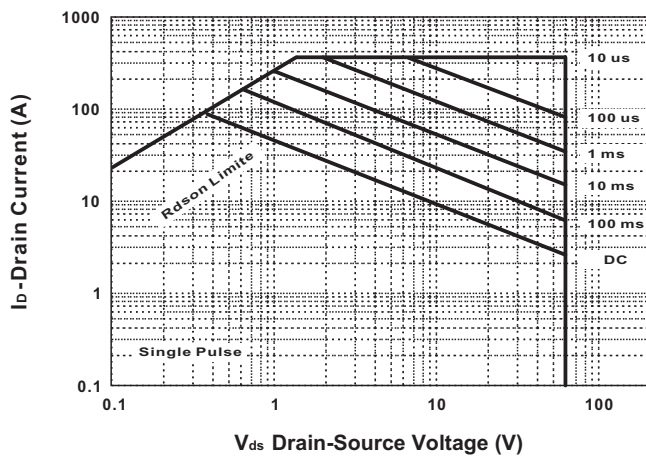


Figure 4: Typical Transfer Characteristics

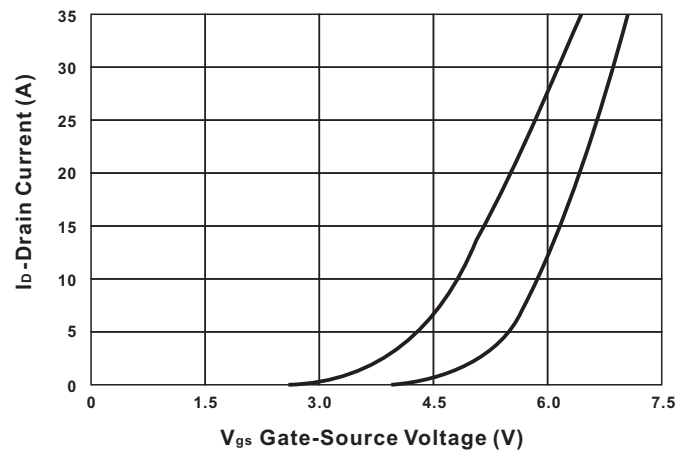


Figure 5: Thermal Transient Impedance

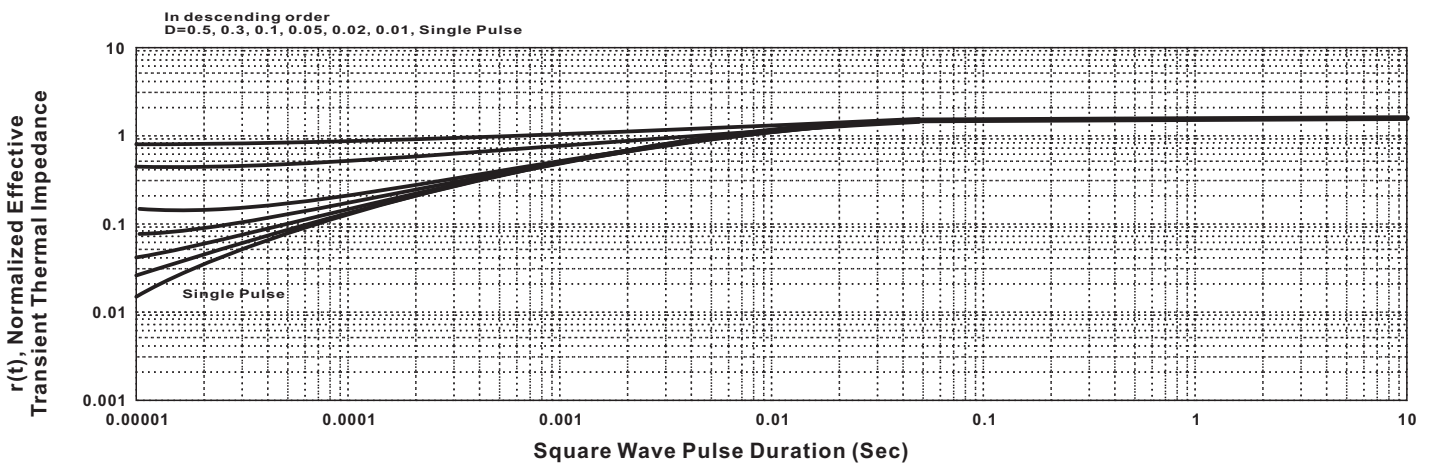


Figure 6: Output Characteristics

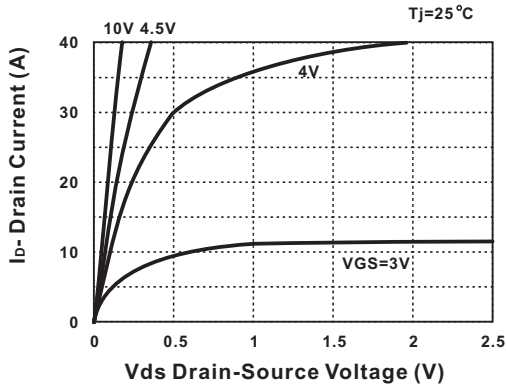


Figure 7: Drain-Source On Resistance

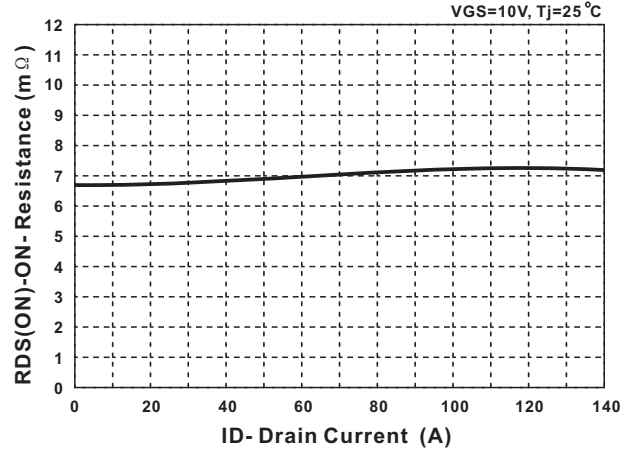


Figure 8: On-Resistance vs. Temperature

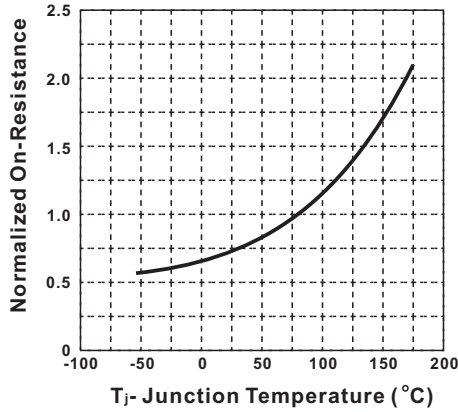


Figure 9: Source-Drain Diode Forward

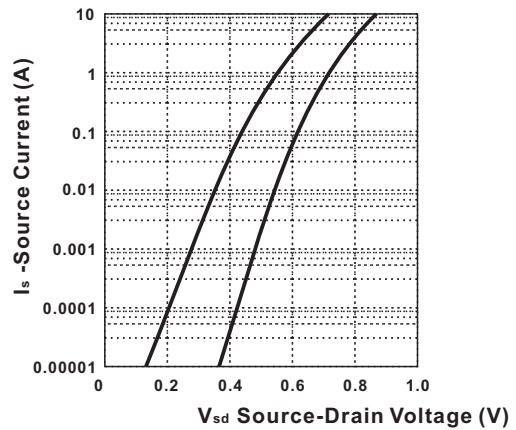


Figure 10: Capacitance Characteristics

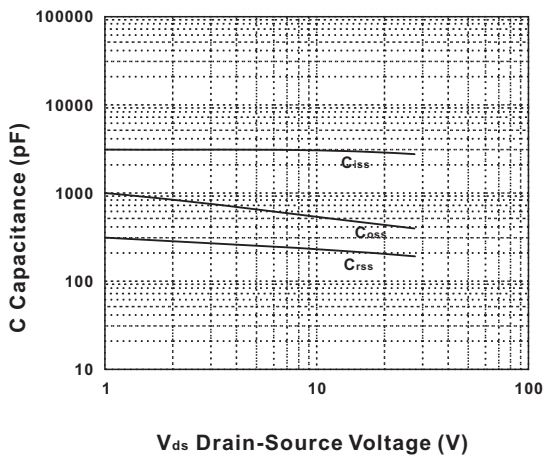
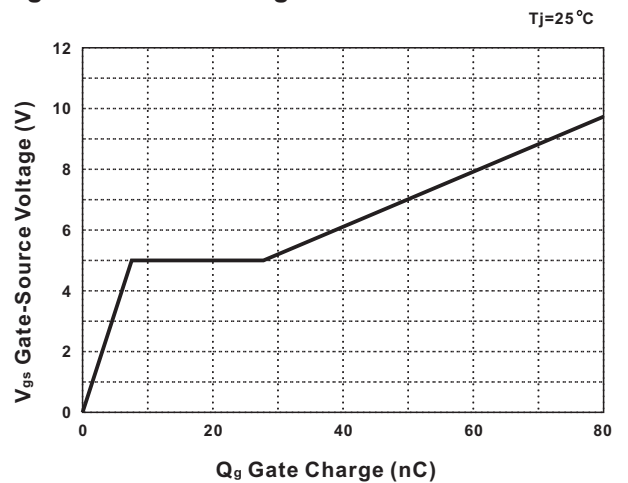
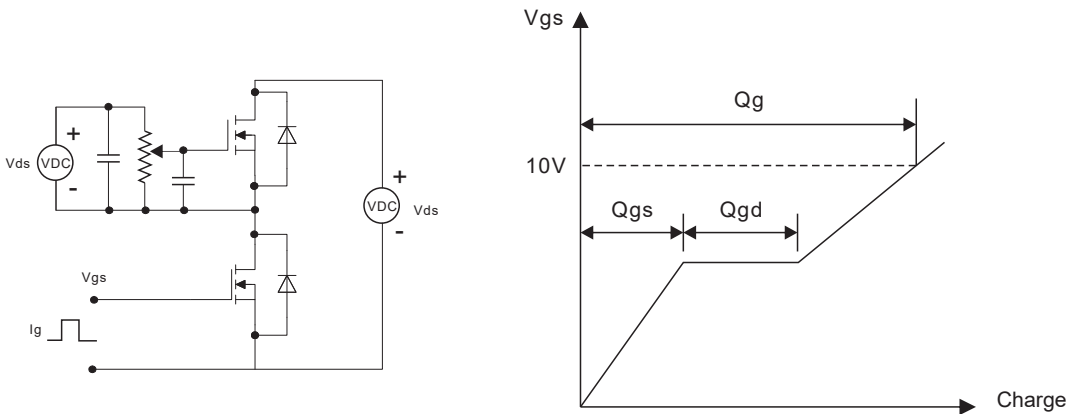


Figure 11: Gate Charge Characteristics

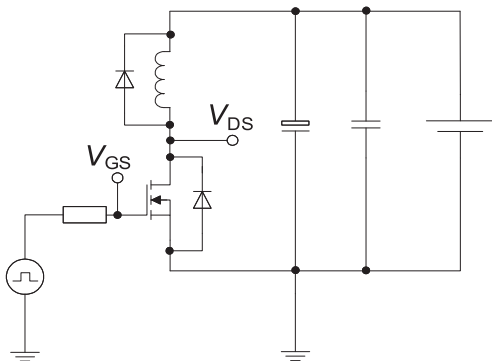


## Test Circuit & Waveform

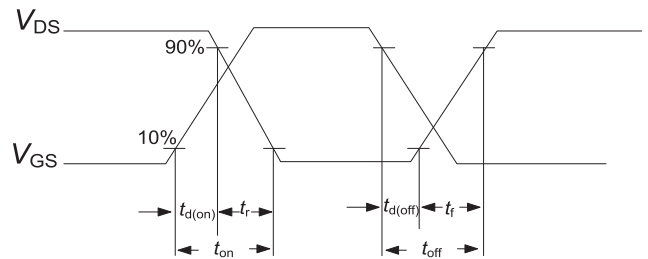
### Gate Charge Test Circuit & Waveform



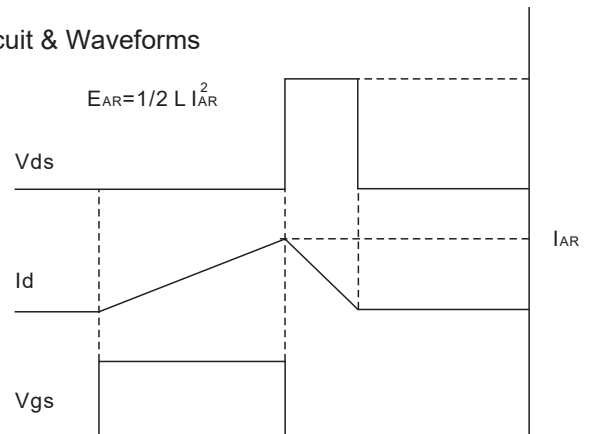
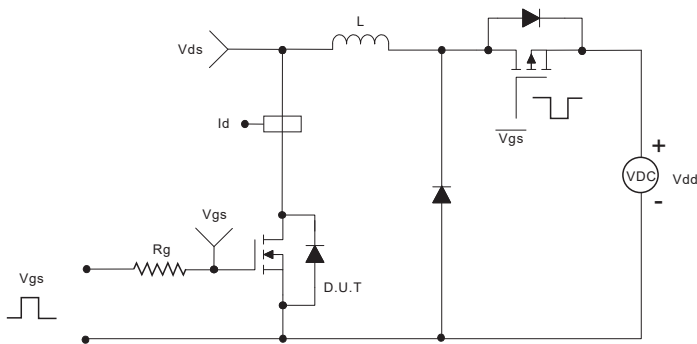
### Switching Times Test Circuit for Inductive Load



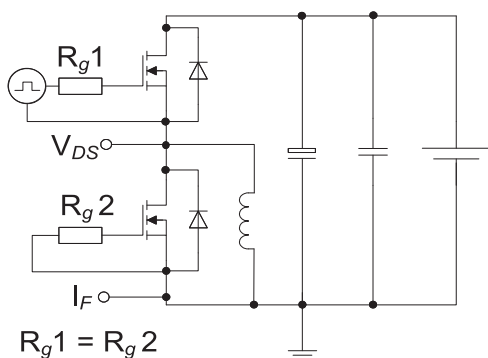
### Switching Times Waveform



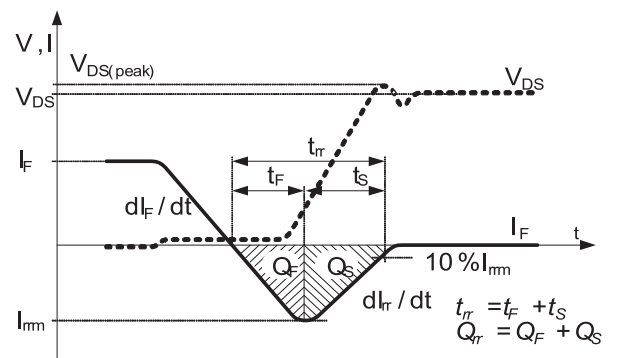
### Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

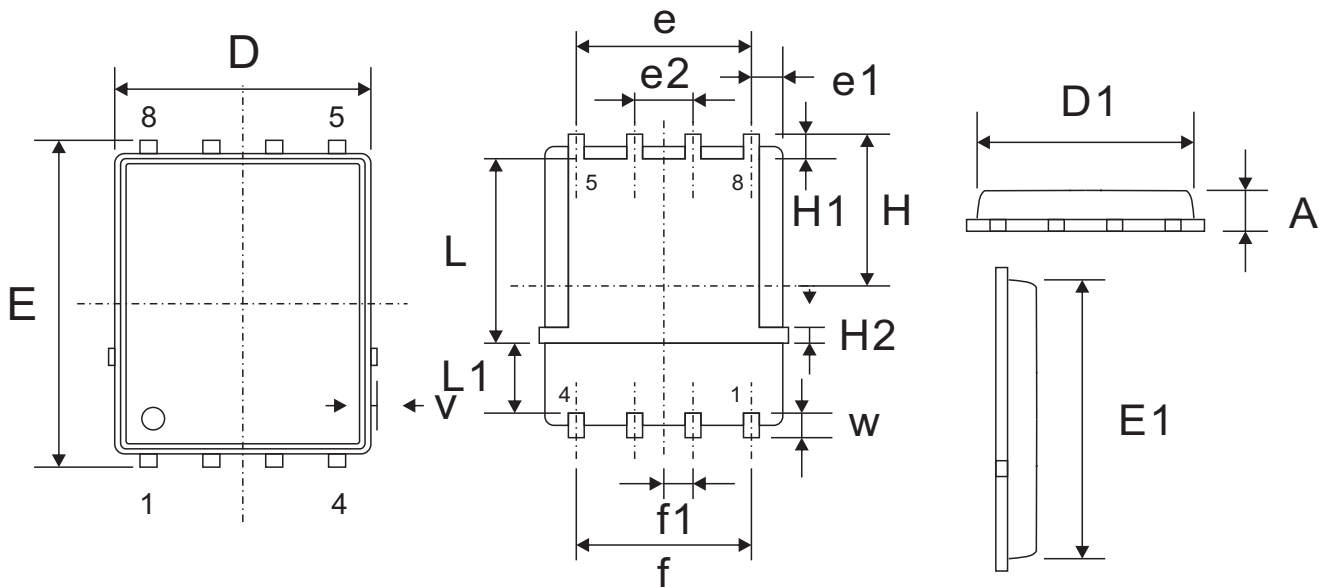


### Test Circuit for Diode Characteristics



### Diode Recovery Waveform



**Package Mechanical Data-PDFN5X6-8L**


Symbol	Dimensions in millimeters	
	Min.	Max.
A	0.90	1.20
D	4.90	5.30
D1	4.80	5.00
E	6.00	6.30
E1	5.65	5.85
e	3.72	3.92
e1	0.54 (Typ.)	
e2	1.27 (Typ.)	
f	3.82 (Typ.)	
f1	0.64 (Typ.)	
H	3.15 (Typ.)	
H1	0.59	0.79
H2	0.26	0.32
L	3.38	3.58
L1	1.39 (Typ.)	
v	0.13 (Typ.)	
w	0.64	0.84

**Revision history**

Date	Revision	Changes
28-May-2020	1.0	Initial release

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